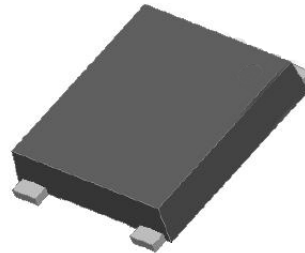
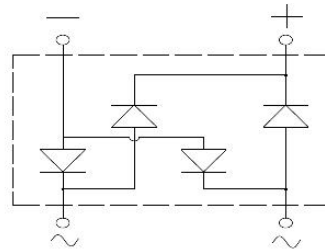


Features

- Glass passivated chip junction
- Ideal for automated placement
- High surge current capability
- Low forward voltage drop
- Design for surface mount application
- Low profile space
- Low leakage current
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2011/65/EU and WEEE 2002/96/EC



RoHS
COMPLIANT



Mechanical Date

- **Case:**DFF
Epoxy meets UL 94 V-0 flammability rating
- **Terminals:**Solder plated, solderable per
J-STD-002 and JESD22-B102
- **Polarity:** Polarity symbols marked on body

Maximum Ratings & Thermal Characteristics TA = 25 °C unless otherwise specified

Parameter		Symbol	DFF 2005	DFF 201	DFF 202	DFF 204	DFF 206	DFF 208	DFF 210	Unit
Maximum repetitive peak reverse voltage		V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage		$V_{R(RMS)}$	35	70	140	280	420	560	700	
Maximum DC blocking voltage		V_{DC}	50	100	200	400	600	800	1000	
Maximum average forward rectified current @60HZ sine wave, R-load $T_L = 80\text{ °C}$		$I_{O(AV)}$	2							A
Non-Repetitive peak forward surge current 8.3ms single half @60HZ, $T_J = 25\text{ °C}$		I_{FSM}	75							A
Operating junction and storage temperature range		T_J, T_{STG}	-55 to +150							°C
Typical thermal resistance per leg	Between junction and ambient	$R_{\theta JA}$	55							°C/W
	Between junction and lead	$R_{\theta JL}$	15							

Electrical Characteristics TA = 25 °C unless otherwise specified

Parameter		Symbol	DFF 2005	DFF 201	DFF 202	DFF 204	DFF 206	DFF 208	DFF 210	Unit
Maximum instantaneous forward voltage	$I_F = 1.0A$	V_{FM}	1.0							V
	$I_F = 2.0A$		1.1							
Peak reverse current at rated DC blocking voltage	$T_A = 25\text{ °C}$	I_{RM}	5							µA
	$T_A = 125\text{ °C}$		300							

Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

FIG1: I_o - T_c Curve

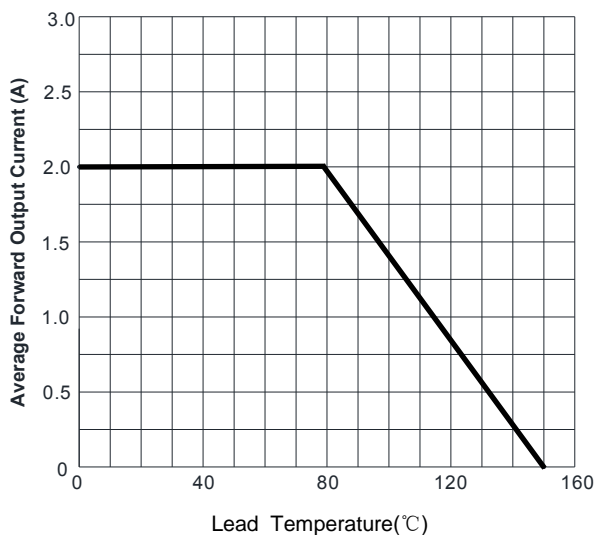


FIG2: Surge Forward Current Capability

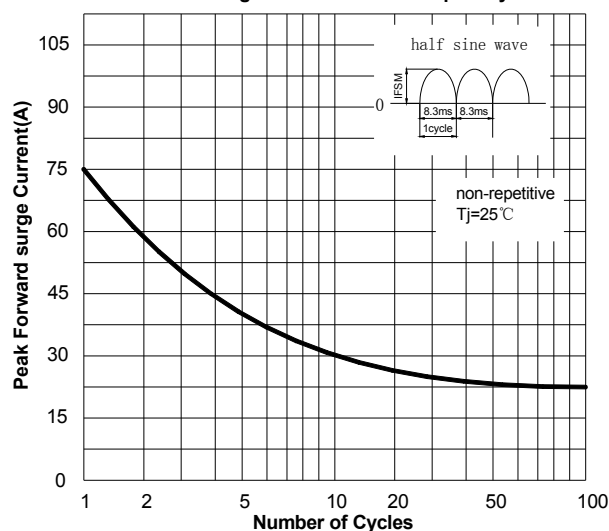


FIG3: Forward Voltage

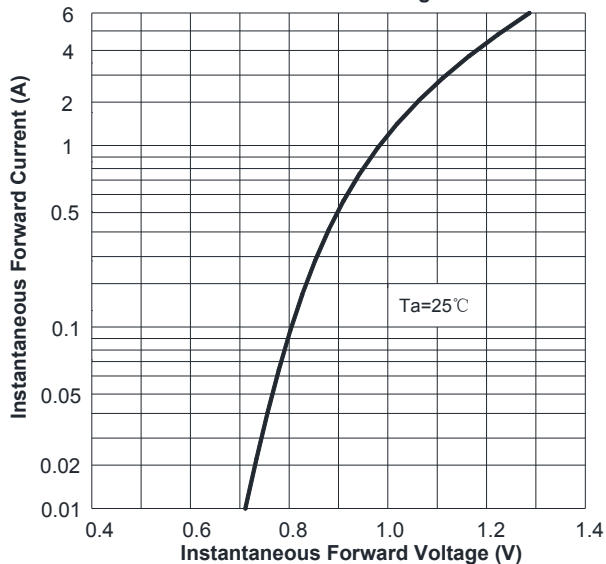
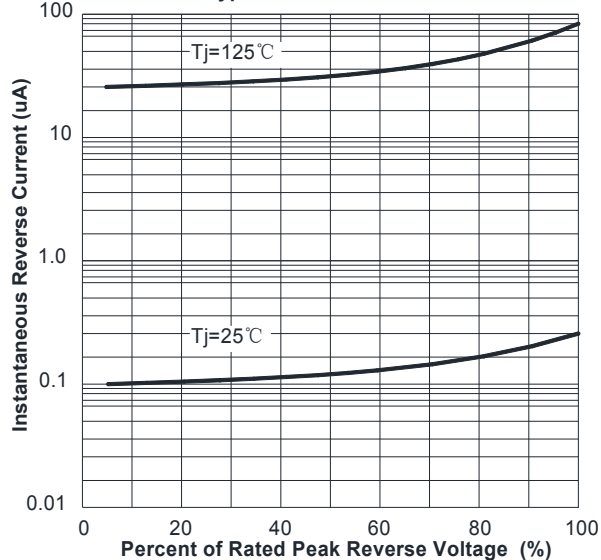
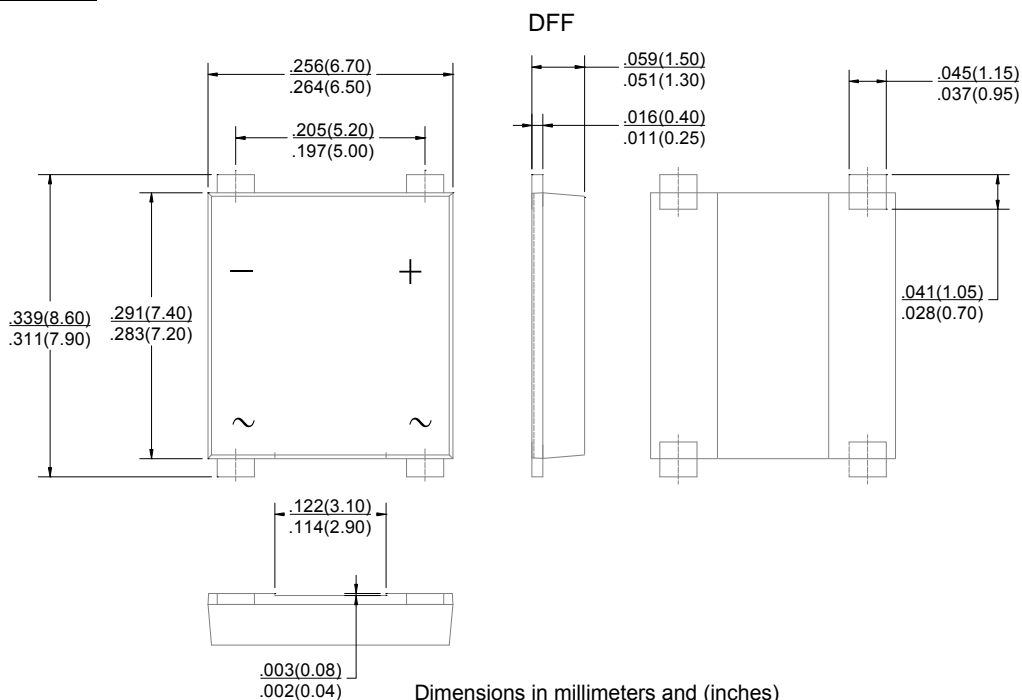


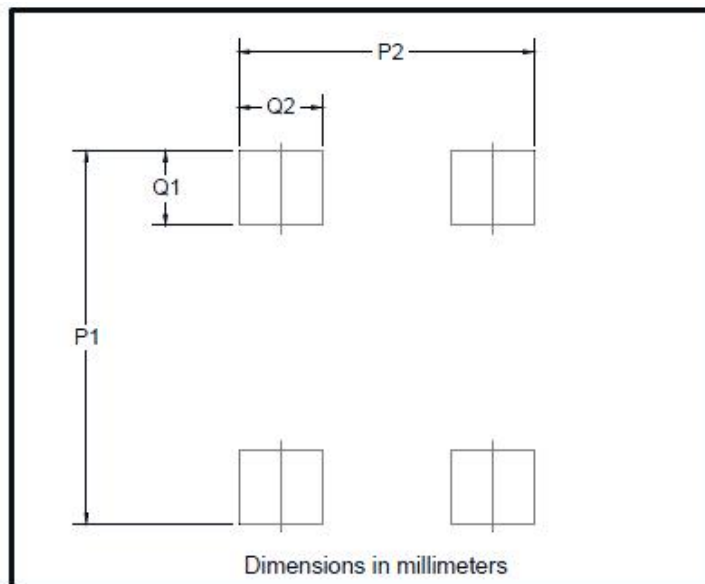
FIG4: Typical Reverse Characteristics



Package Outline



Suggested pad layout



Dim	Min
P1	9.15
P2	7.10
Q1	1.80
Q2	2.00

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